



# 100% Material Declaration Data Sheet PQG240

PK124 (v1.2.1) October 19, 2006

Material Declaration Data Sheet

**Average Weight: 7.1 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.08023</b>	<b>1.13%</b>
	Silicon	7440-21-3	100.00		0.08023	
<b>Die Attach Material</b>					<b>0.01065</b>	<b>0.15%</b>
	Silver	7440-22-4	78.00		0.008307	
	Epoxy (EP)	Trade Secret	22.00		0.002343	
<b>Mold Compound</b>					<b>5.72828</b>	<b>80.68%</b>
	Epoxy Resin (EP)	Trade Secret	9.00		0.5155452	
	Phenolic Resin	Trade Secret	7.00		0.4009796	
	Carbon Black	1333-86-4	0.50		0.0286414	
	Silica	60676-86-0	82.50		4.725831	
	Bismuth	7440-69-9	Max 1.00		0.0572828	
<b>Leadframe</b>					<b>0.79236</b>	<b>11.16%</b>
	Copper	7440-50-8	98.85		0.78324786	
	Chromium	7440-47-3	0.30		0.00237708	
	Tin	7440-31-5	0.25		0.0019809	
	Zinc	7440-66-6	0.60		0.00475416	
<b>Leadframe Plating</b>					<b>0.00497</b>	<b>0.07%</b>
	Silver	7440-22-4	100.00		0.00497	
<b>Bond Wire</b>					<b>0.0128</b>	<b>0.18%</b>
	Gold	7440-57-5	100.00		0.0128	
<b>Heatspreader</b>					<b>0.42813</b>	<b>6.03%</b>
	Alumiumim	7429-90-5	100.00		0.42813	
<b>Ext. Plating</b>					<b>0.0426</b>	<b>0.60%</b>
	Tin	7440-31-5	100.00		0.0426	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/08/06	1.0	Initial release.
7/05/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.
10/19/06	1.2.1	Editorial change; corrected typo in Substance Description.